

Title (en)

METHOD AND DEVICE FOR TREATING TABULAR SUBSTRATES, ESPECIALLY SILICON WAFERS FOR PRODUCING MICROELECTRONIC ELEMENTS

Title (de)

VERFAHREN UND VORRICHTUNG ZUM BEHANDELN VON FLÄCHIGEN SUBSTRATEN, INSBESONDERE SILIZIUM-SCHEIBEN (WAFER) ZUR HERSTELLUNG MIKROELEKTRONISCHER BAUELEMENTE

Title (fr)

PROCEDE ET DISPOSITIF DE TRAITEMENT DE SUBSTRATS PLATS, EN PARTICULIER DE TRANCHES DE SILICIUM POUR LA FABRICATION DE COMPOSANTS MICROELECTRONIQUES

Publication

EP 1153421 A1 20011114 (DE)

Application

EP 99904791 A 19990118

Priority

EP 9900252 W 19990118

Abstract (en)

[origin: WO0042637A1] The invention relates to a method and to a device for treating tabular substrates (5) according to which said substrate (5) is arranged in a narrow gap (62) between two plates (60, 61).

IPC 1-7

H01L 21/00

IPC 8 full level

H01L 21/00 (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP KR)

H01L 21/30 (2013.01 - KR); **H01L 21/67051** (2013.01 - EP)

Citation (search report)

See references of WO 0042637A1

Designated contracting state (EPC)

AT CH DE FR GB IT LI NL

DOCDB simple family (publication)

WO 0042637 A1 20000720; AU 2518399 A 20000801; EP 1153421 A1 20011114; JP 2002535831 A 20021022; KR 20020018183 A 20020307

DOCDB simple family (application)

EP 9900252 W 19990118; AU 2518399 A 19990118; EP 99904791 A 19990118; JP 2000594139 A 19990118; KR 20017008992 A 20010716